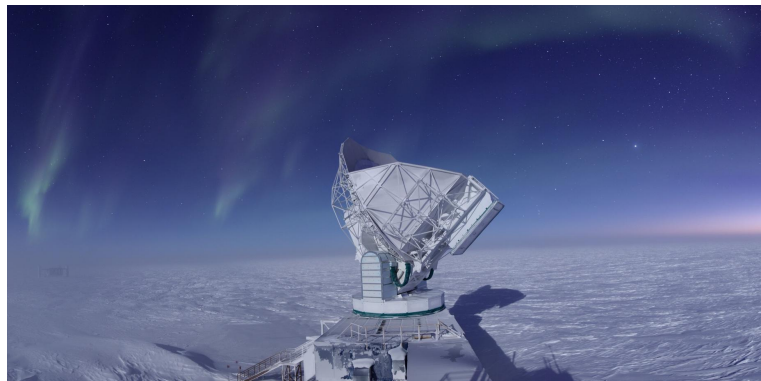


MKID development for the SPT-3G+ camera on the South Pole Telescope

Karia Dibert
(for the SPT-3G+ collaboration)
CPAD 2023

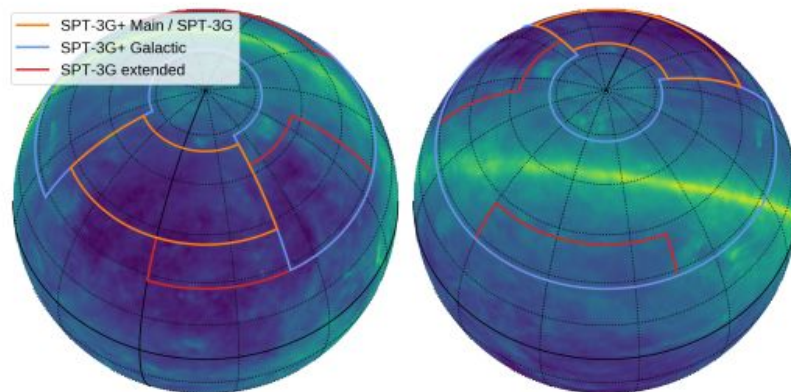
SPT-3G+: A new camera for the South Pole Telescope



J. Gallicchio

The South Pole Telescope

- 10-meter millimeter/submillimeter telescope that observes the Cosmic Microwave Background (CMB)
- Uniquely dry & stable South Pole atmosphere is ideal for CMB observations.
- Currently equipped with SPT-3G camera:
 - Observes the CMB at 95, 150 and 220 GHz
 - 14,000 TES bolometers



A. Anderson

SPT-3G+ Survey

- High-frequency, high-sensitivity complement to the SPT-3G dataset!
 - Will observe at 220, 285, and 345 GHz
- On-sky demonstration of detector technology
 - The camera will consist of 34,000 Microwave Kinetic Inductance Detectors (MKIDs)

SPT-3G+ Science



Recombination

First detection of Rayleigh scattering of the CMB, a new probe of cosmic expansion and ionization history.

Reionization

Constrain the time and duration of reionization via the kinematic Sunyaev-Zel'dovich effect.

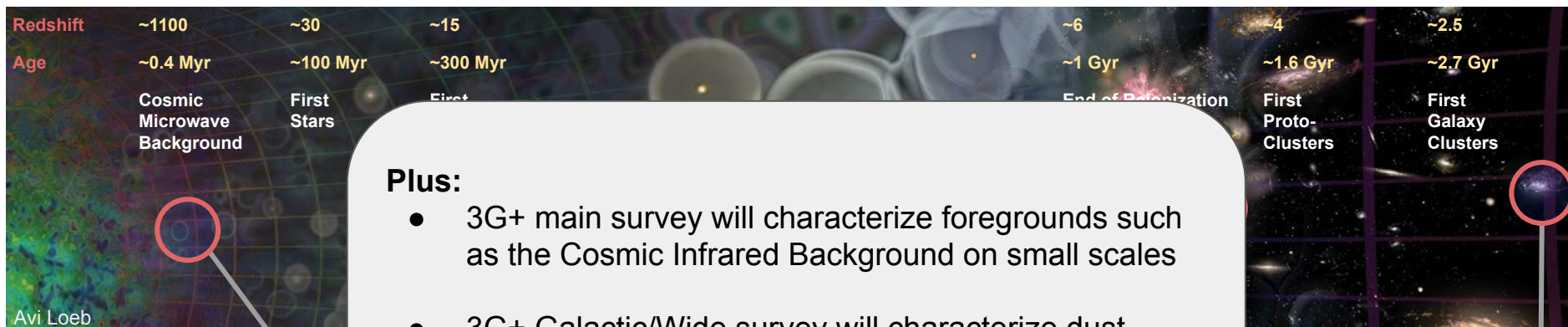
Galaxy & Cluster Growth

Detect dusty emission from very distant massive galaxies and clusters to learn more about their formation and evolution.

Cluster Finding

Identify new galaxy clusters via the thermal Sunyaev-Zel'dovich effect.

SPT-3G+ Science



Plus:

- 3G+ main survey will characterize foregrounds such as the Cosmic Infrared Background on small scales
- 3G+ Galactic/Wide survey will characterize dust emission for wide-field lensing reconstruction and study small-scale galactic magnetic fields
- 3G+ will extend SPT transient measurements into the VRO/LSST area at mm/sub-mm wavelengths

Recombination

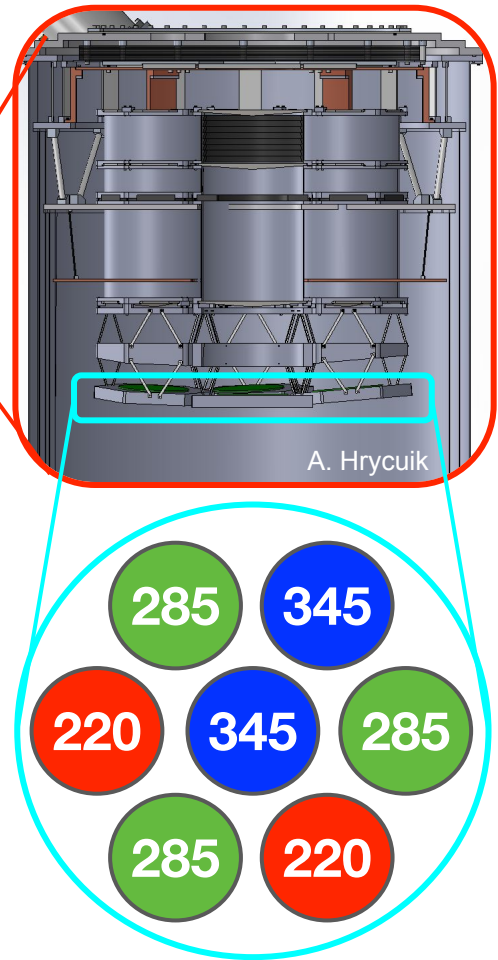
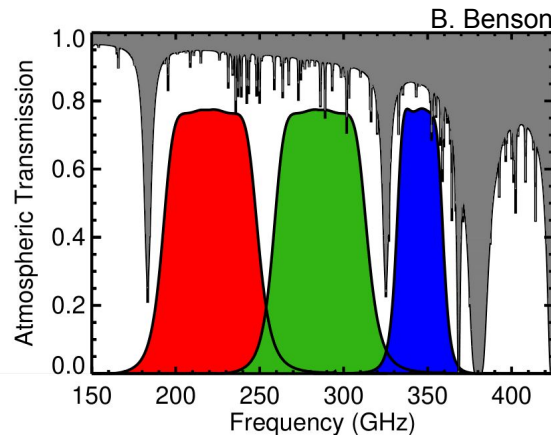
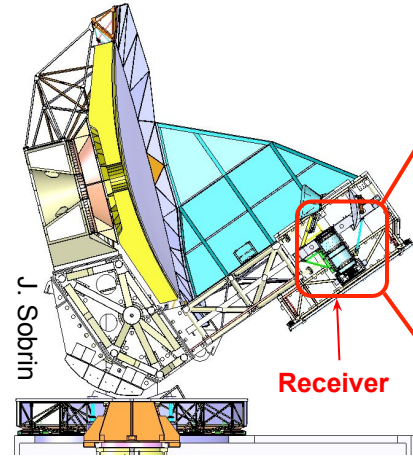
First detection of Rayleigh scattering of the CMB, a new probe of cosmic expansion and ionization history.

Cluster Finding

Identify new galaxy clusters via the thermal Sunyaev Zel'dovich effect.

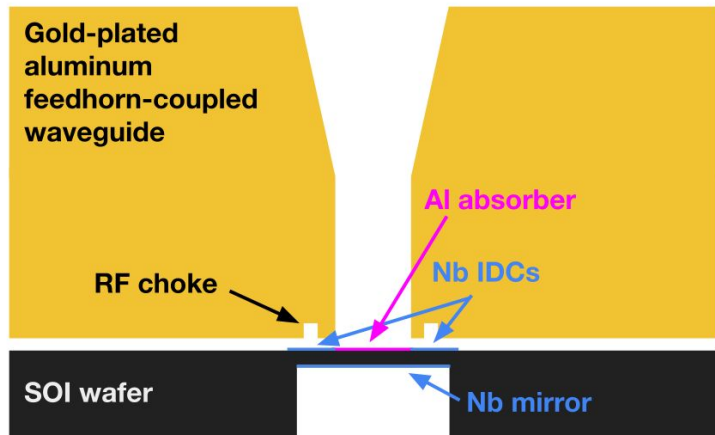
SPT-3G+ Receiver

- Seven separate optics tubes, each illuminating a wafer of 4800 monochroic polarization-sensitive MKIDs.
 - MUX goal is 800 detectors per 500 MHz readout bandwidth, or 6 feedlines per wafer.
 - **34k total detectors.**
 - Readout with McGill RF-ICE system modified for MKID readout (Rouble, et al. 2023 - arXiv:2310.07657)
- Separate optics tubes allow for individual wafer upgrades - potential future platform for Line Intensity Mapping (see talk by K. Karkare)

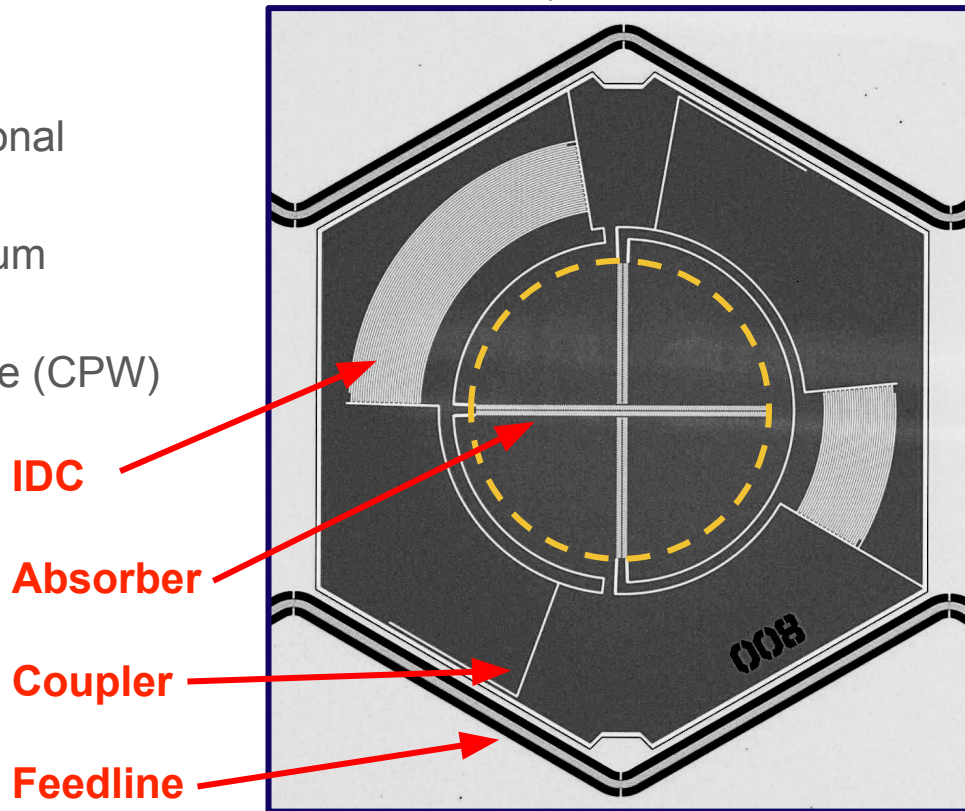


Pixel design

- Feedhorn-coupled single-frequency direct-absorber MKID
- 2x detectors per pixel, coupled to orthogonal polarization modes
- Aluminum inductors/absorbers and niobium interdigitated capacitors (IDCs)
- Feedline is a niobium coplanar waveguide (CPW)

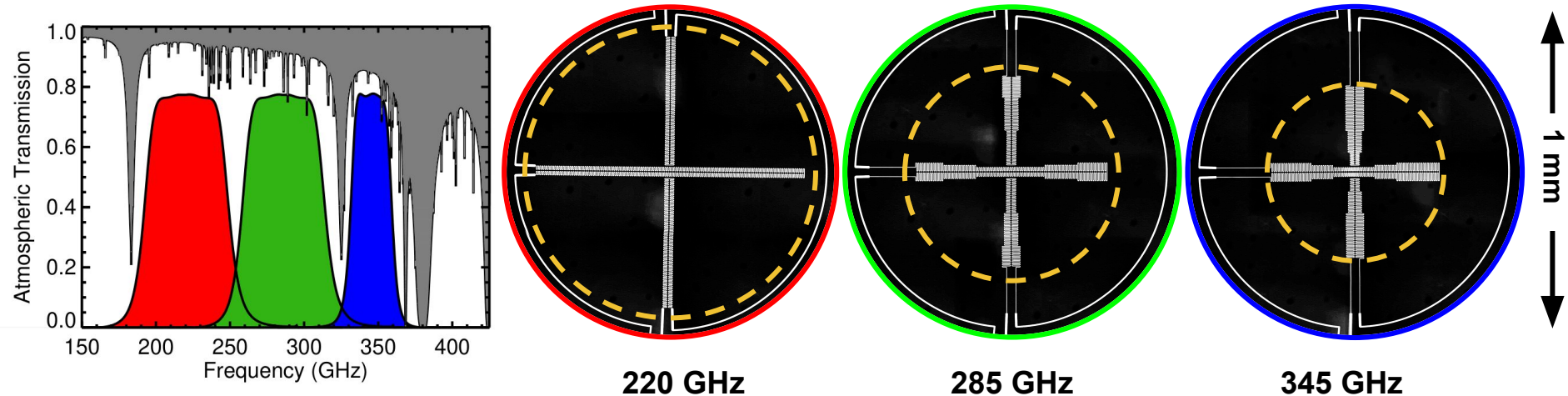


Dibert, Barry et al. 2022 - arXiv:2111.04816



Absorber design

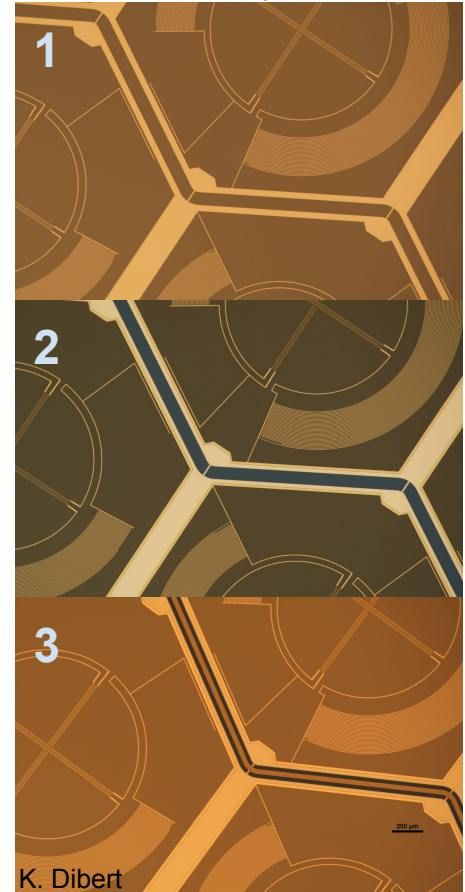
- Aluminum inductors meander to achieve the necessary volume to support the expected optical load ($\sim 5\text{-}10$ pW) at the South Pole.
- Simulations indicate good ($\sim 80\text{-}90\%$) optical coupling and low ($\sim 2\text{-}3\%$) cross-polarization pickup.



Device fabrication

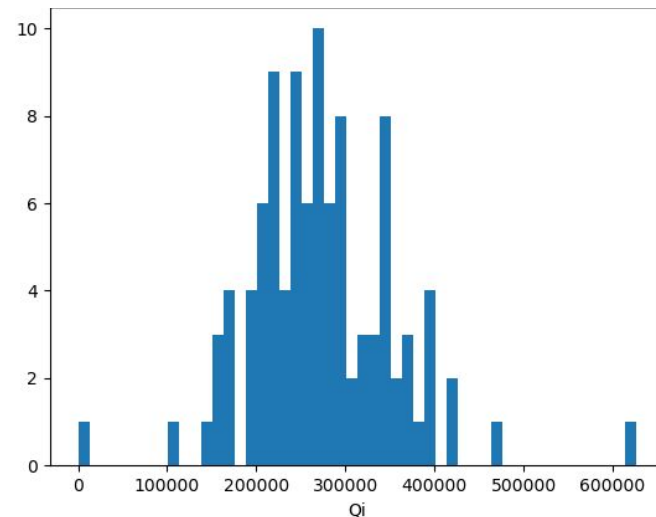
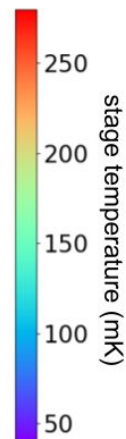
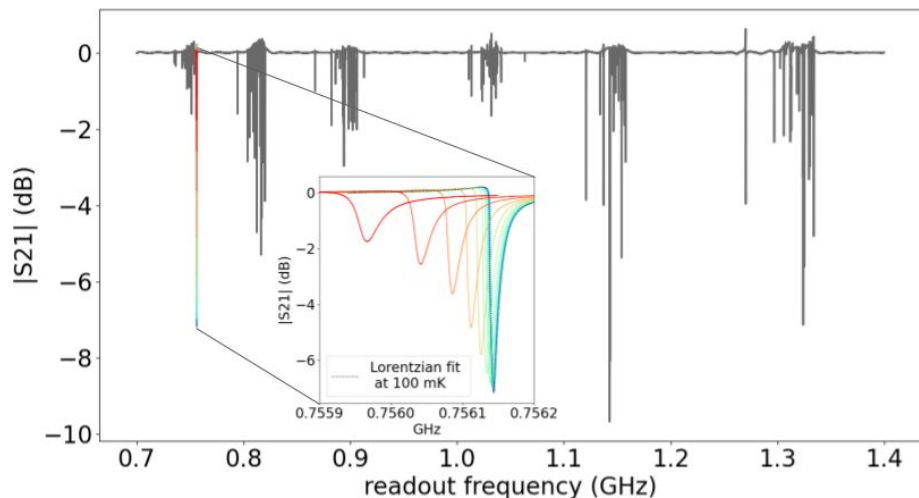
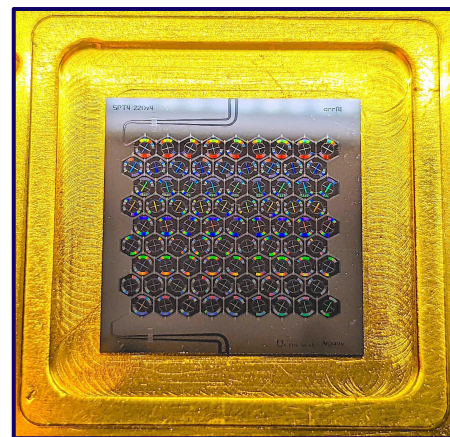
- Device fabrication process:
 - Inductors/absorbers (30nm Al)
 - IDCs, ground plane, CPW bridges (120nm Nb)
 - Bridge layer (150nm SiO₂) ← *for now!*
 - Feedline (200nm Nb)
- Initial prototypes are fabricated at UChicago (me), and larger arrays of chips/subarrays are fabricated at Argonne.
 - Eventually, deployment-grade arrays will be made at Argonne
- More work at Argonne on SPT-3G+ fab:
 - Galvanic contact via NbN interface and SiN membrane stepdown (Cecil, et al. 2023, arXiv:2304.00973)
 - Response of two-level-system noise to IDC geometry (Pan, et al. 2023, arXiv:2304.01133)
 - Effect of varying inductor linewidth on resonant frequency scatter (Li, et al. 2022, arXiv:2203.17244)

CPW fabrication process

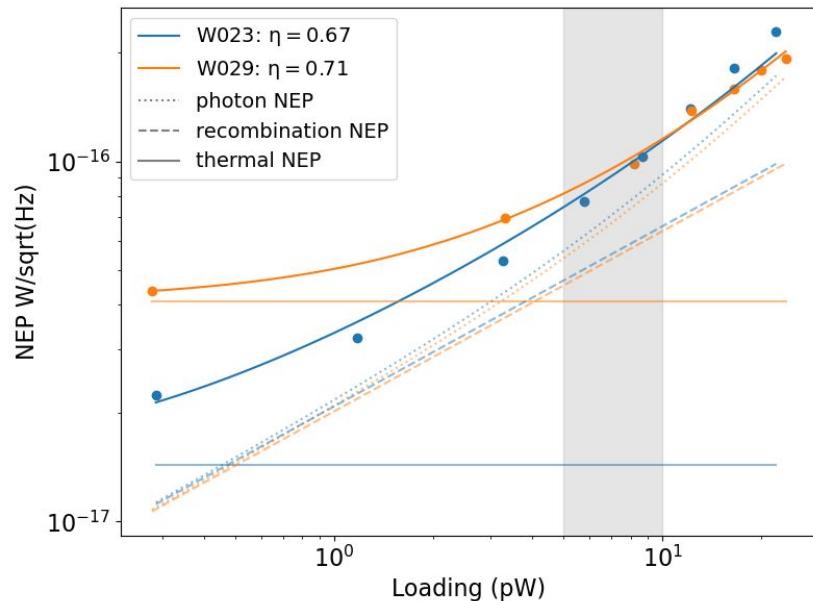


Dark tests look good for 1x1 inch chips!

Repeatedly achieved mean $Q_i > 100k$ and the expected response to stage heating from these test chips, each with 50-80 pixels.

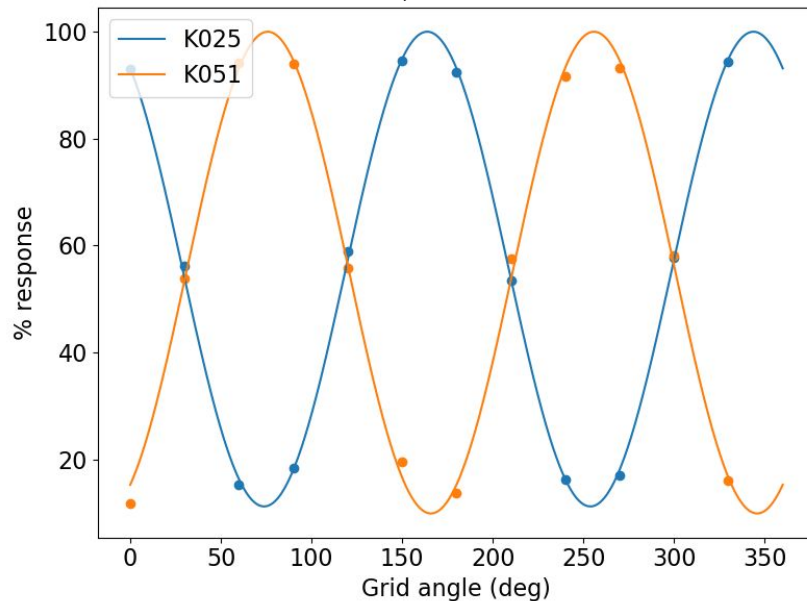


Optical testing for 220 GHz



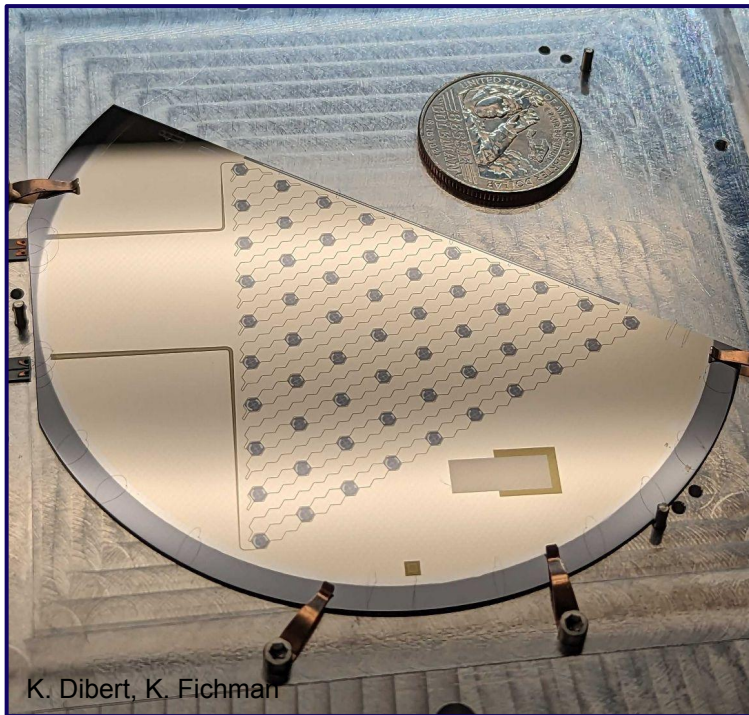
- We see background-dominated response from 220 GHz detectors at the expected SPT optical loading (grey band).
- Fit to NEP vs loading gives $\sim 70\%$ optical efficiency (from feedhorn to detector).

Dibert, et al. 2023 - arXiv:2304.01158

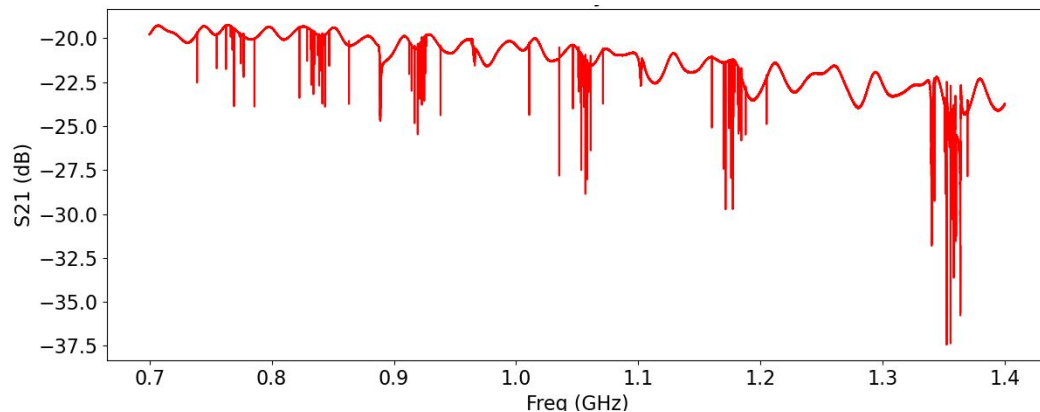


- We see the expected response to polarization angle for two orthogonally-aligned detectors
- Cross-polarization pickup of $< 10\%$ (conical feedhorn included)

Scaling up to deployment-sized arrays



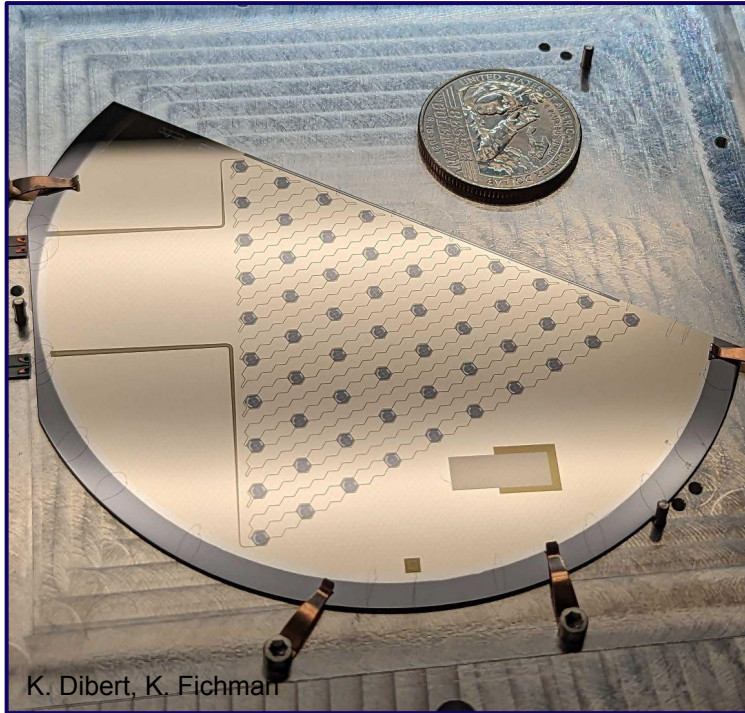
1/7 filled triangle subarray feedline test
UChicago 100mm wafer



Mean $Q_i \sim 200k$
Yield 91% (101/110)

Same as the 1x1 inch chips, so add
more pixels!

Scaling up to deployment-sized arrays

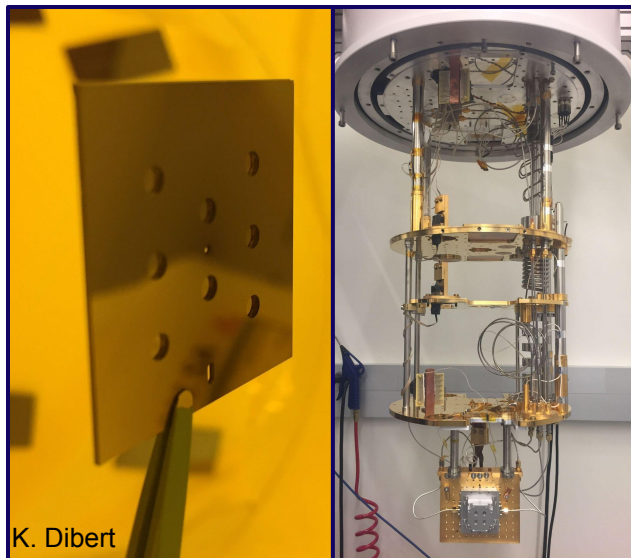


1/7 filled triangle subarray feedline test
UChicago 100mm wafer



1/4 filled triangular subarrays for 3 bands
Argonne 150mm wafer

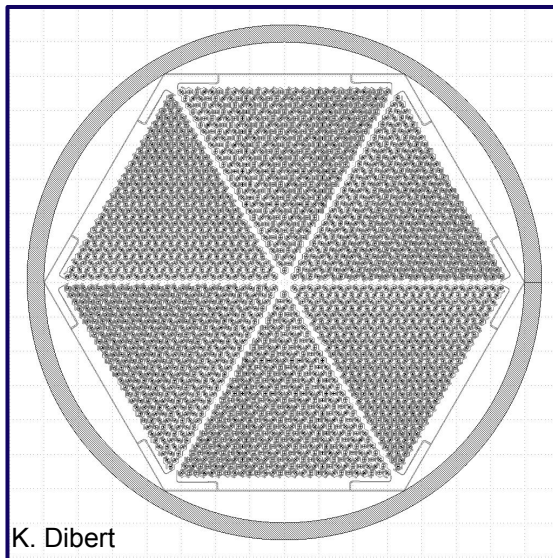
Upcoming plans



K. Dibert

Fabrication and optical testing of 345 GHz and 285 GHz prototype chips on appropriate SOI wafers.

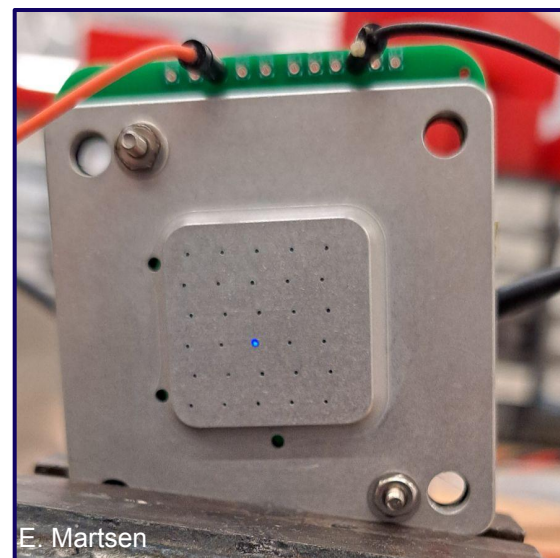
- Repeat the process that we did for 220 GHz!



K. Dibert

Fabrication and dark testing of fully-filled subarrays.

- 150mm wafers will be fabricated at Argonne!



E. Martsen

Pixel identification via LED mapper for post-fabrication IDC trimming - necessary for mux goals.

Thank you!



Berkeley
UNIVERSITY OF CALIFORNIA



CARDIFF
UNIVERSITY



McGill
UNIVERSITY

SLAC

PRIFYSGOL
CAERDYDD



University of Colorado
Boulder

